

# Vapor Phase Doping of Boron in Silicon

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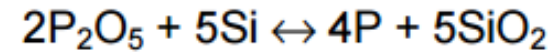
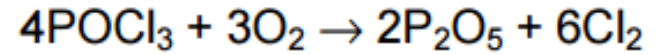
**PI: Prof. James Harris**

# Outline

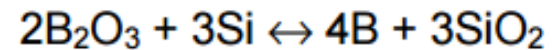
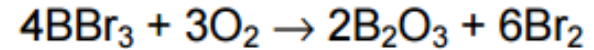
- Motivation
  - SNF
  - Broader sense
- Methodology
  - Epi
  - Sheet resistance measurement
- Deposition @ 900°C
- Conclusion

# Doping Predep Furnace

- POCl<sub>3</sub> (Phosphor)
  - Tylan 6, works OK
  - BOE remove oxide



- BBr<sub>3</sub> (Boron)
  - Tylan 5
  - Not working, hard to remove oxide



- Vapor phase doping
  - Epi2
  - B<sub>2</sub>H<sub>6</sub> in H<sub>2</sub> environment
    - 100ppm – 0.01ppm
  - No epitaxy growth
- Interesting application
  - DUV / EUV photodiode
    - 2nm p+ type layer
    - 193nm → absorption length: 5.5nm
  - Alternative to ion implantation
    - TED-free (Transient Enhanced Diffusion)
    - Selective area doping → oxide hard mask
    - Sidewall doping

# Methodology – Epi

- **Temperature**
  - 700°C / 800°C / 900°C
- **Pressure**
  - 10-100 Torr
- **B<sub>2</sub>H<sub>6</sub> flow rate**
  - 100ppm – 0.01ppm
- **B<sub>2</sub>H<sub>6</sub> flow time**
  - 1s – 30min

# Methodology – Epi

- **Temperature**

~~– 700°C~~ / 800°C / 900°C

→ significance difference  
in doping dynamics

- **Pressure**

~~– 10-100 Torr~~

→ Doesn't matter

- **B<sub>2</sub>H<sub>6</sub> flow rate**

– 100ppm – 0.01ppm

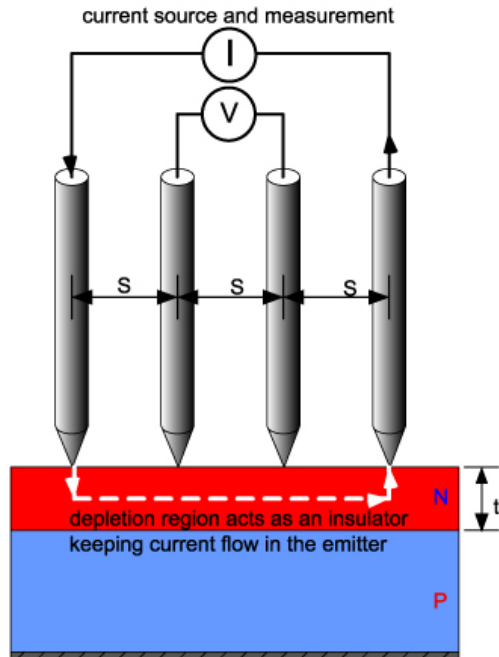
→ Less important

- **B<sub>2</sub>H<sub>6</sub> flow time**

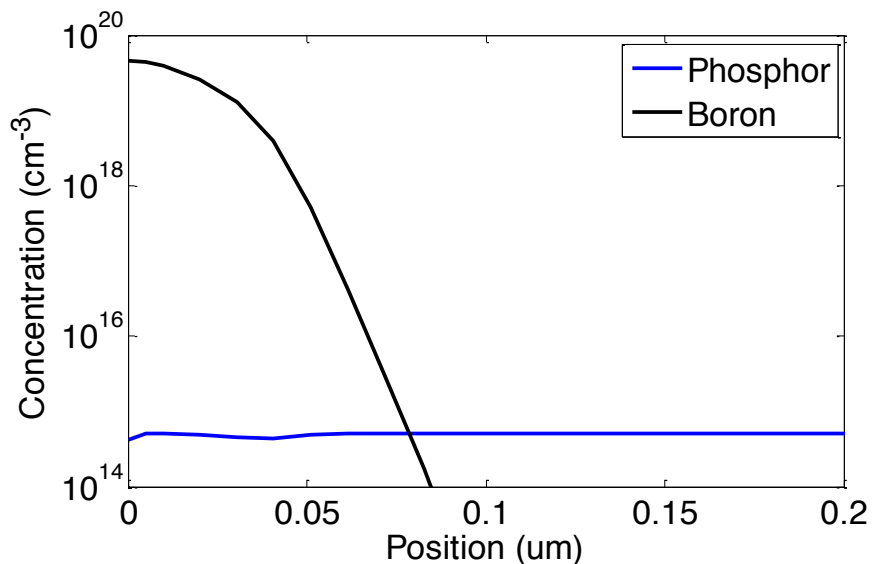
– 1s – 30min

→ More important

# Methodology -Four point probe

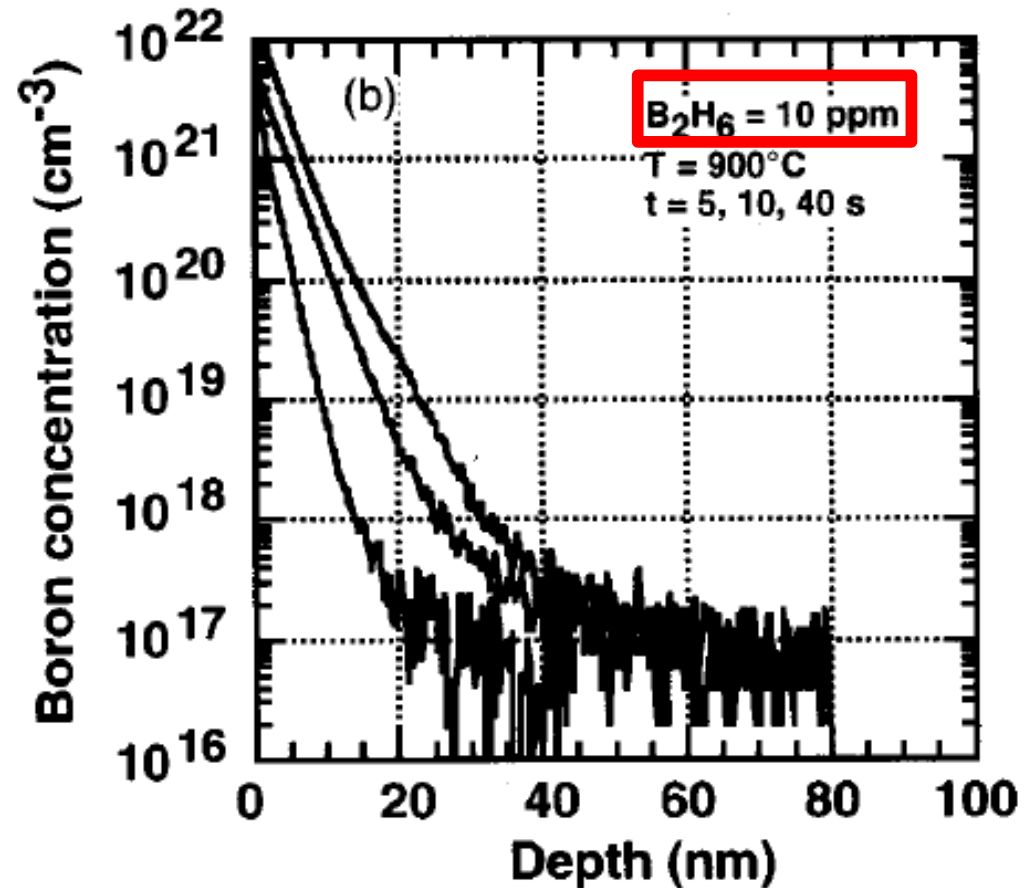
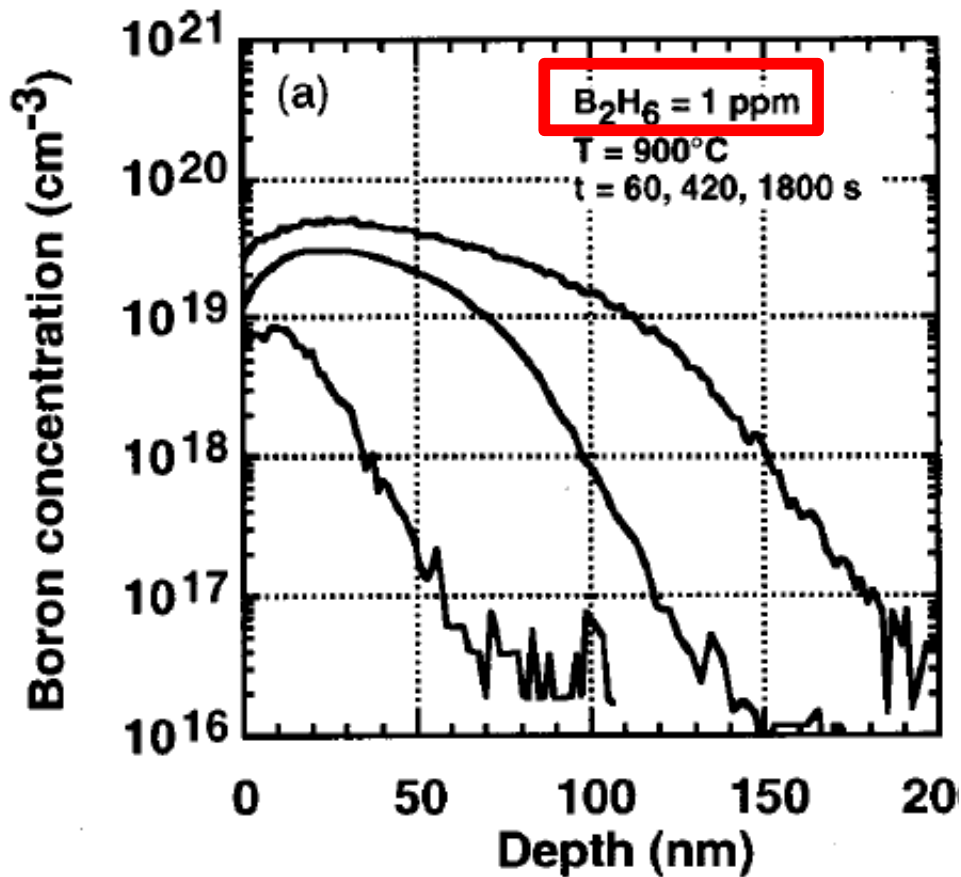


- Test wafer
  - C test
  - Phosphor:  $6 \times 10^{14} - 1 \times 10^{15} \text{ cm}^{-3}$



- Sheet resistance
  - 1,048 Ohm/[]

# Doping @ 900°C



**Doping at 900°C could potentially make all Boron electrically active**

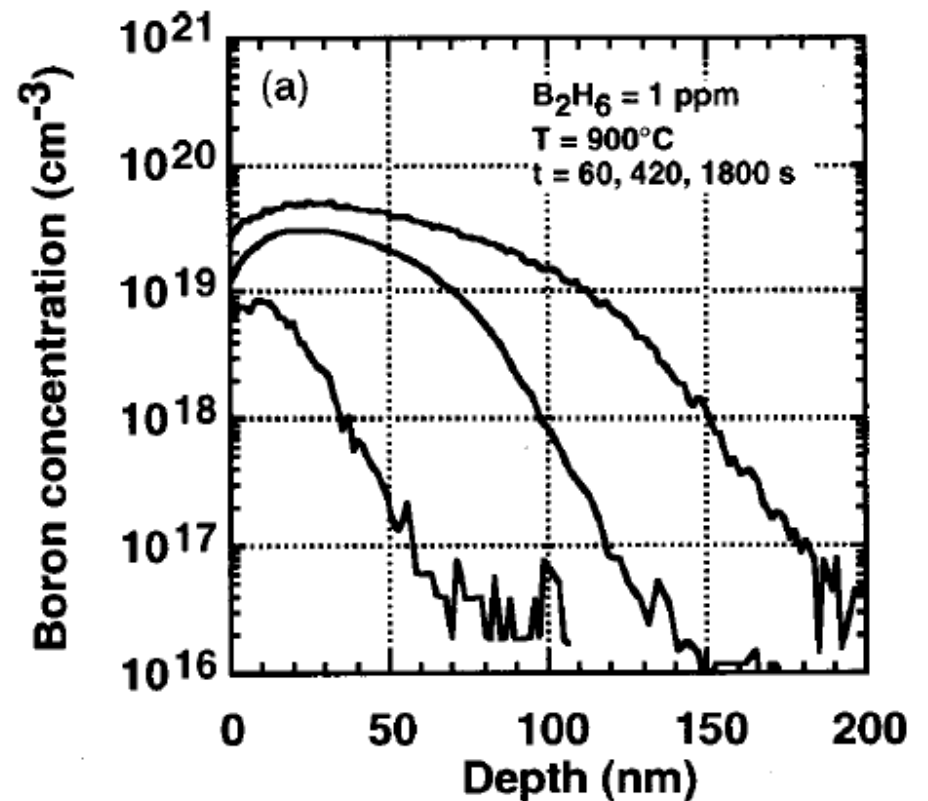
$\text{B}_2\text{H}_6 < 1 \text{ ppm}$ , Boron is electrically active

$\text{B}_2\text{H}_6 > 10 \text{ ppm}$ , Boron segregates on surface  $\rightarrow$  not  $\alpha\text{-B}$ ,  $\text{B}_x\text{Si}$

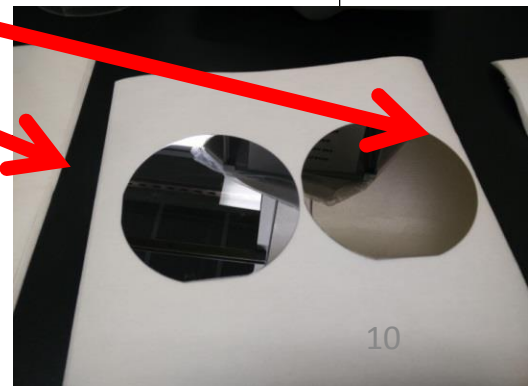
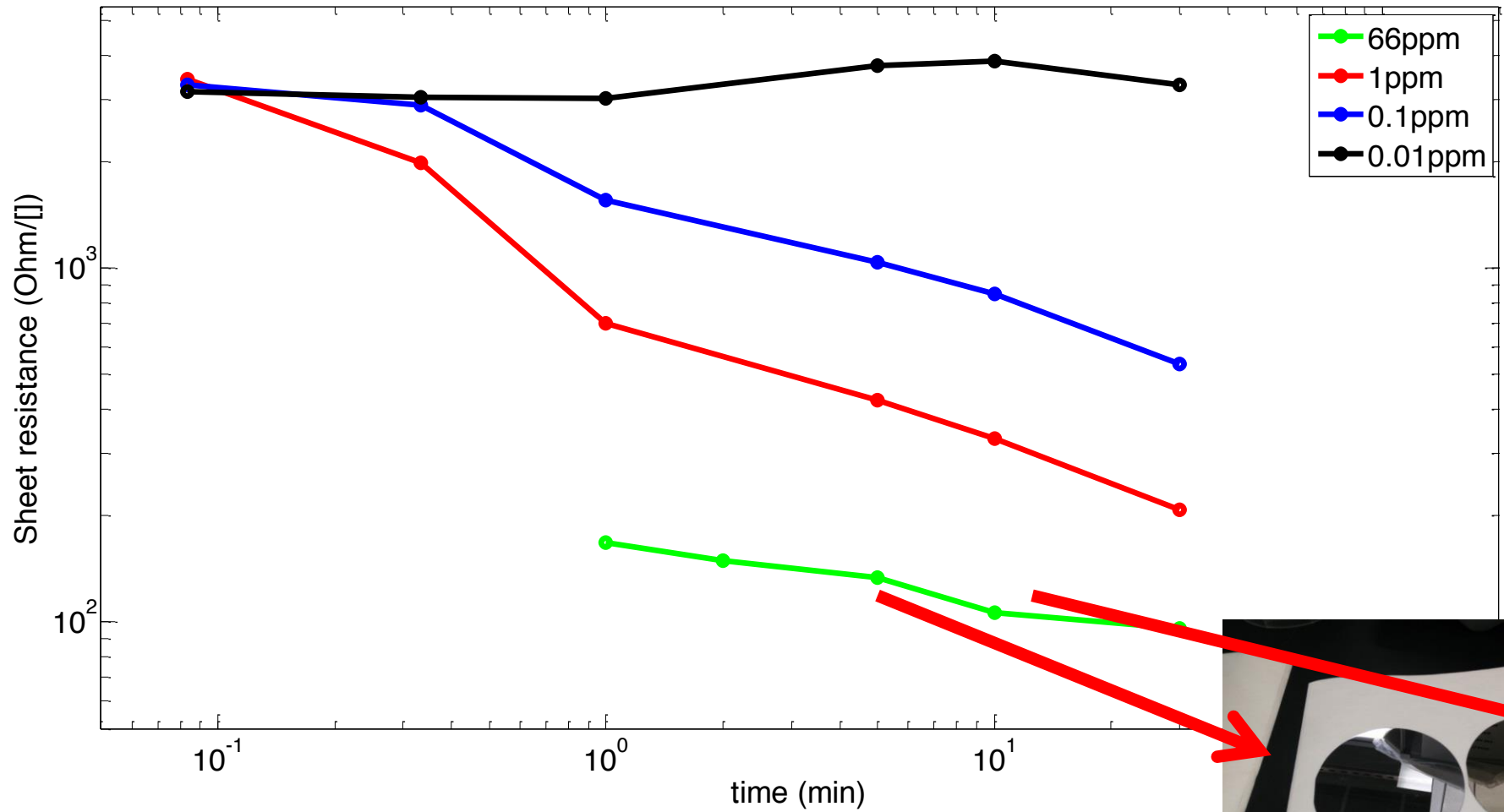


# Modelling

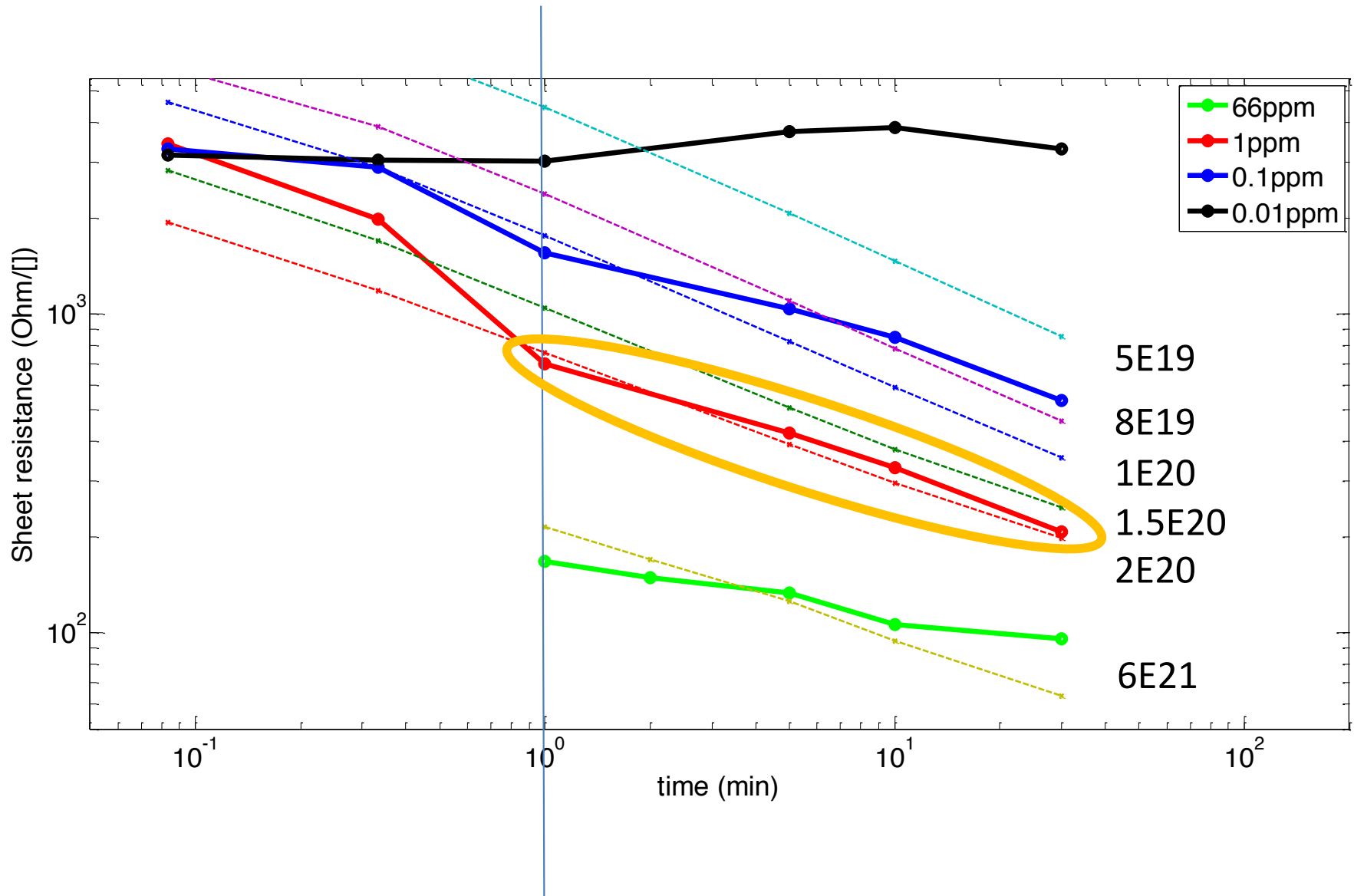
- Constant  $C_s$ 
  - $\text{Erfc}(x)$
- Diffuse to Si
- Out-diffusion from Si



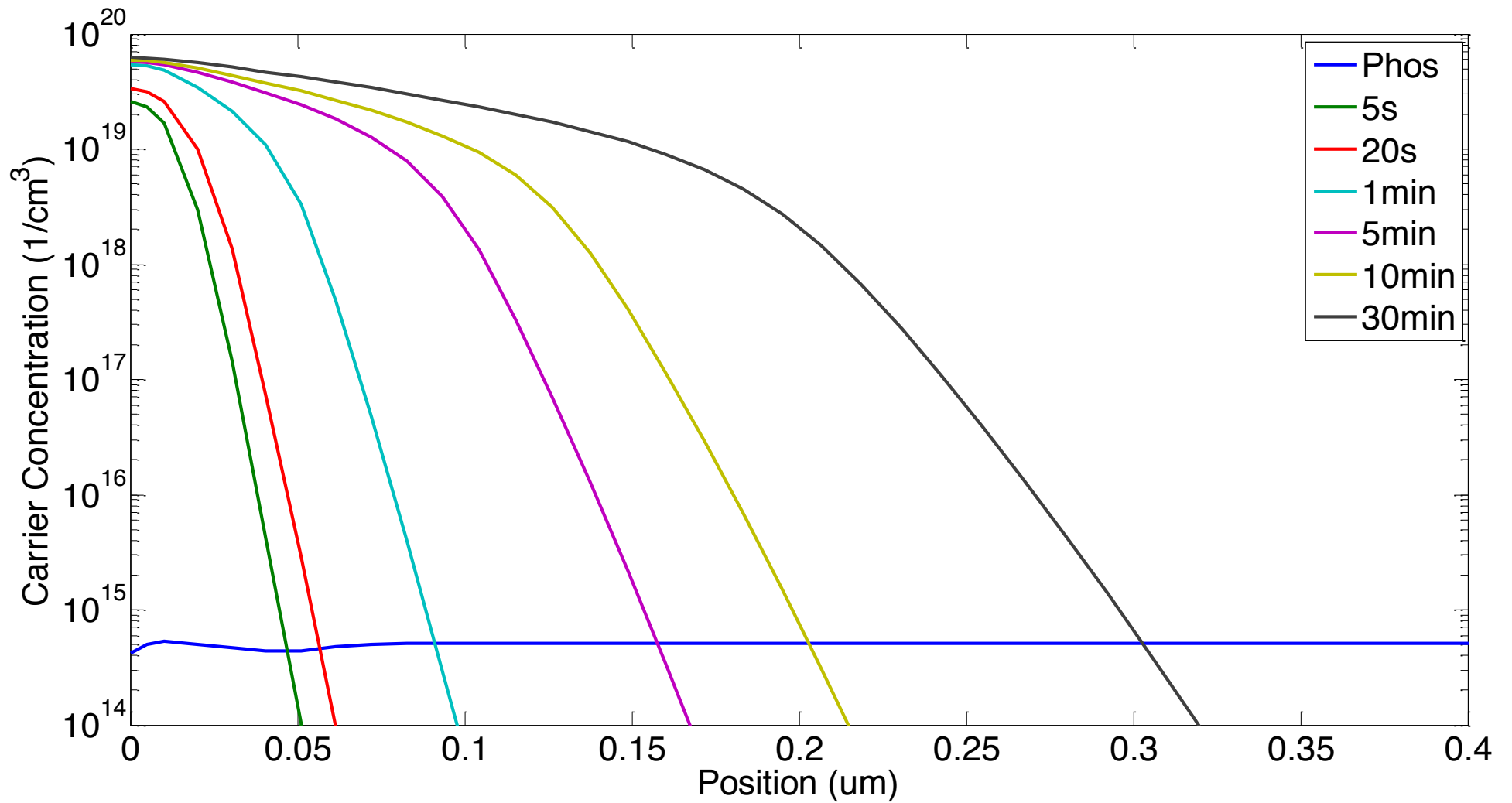
# Experiment result



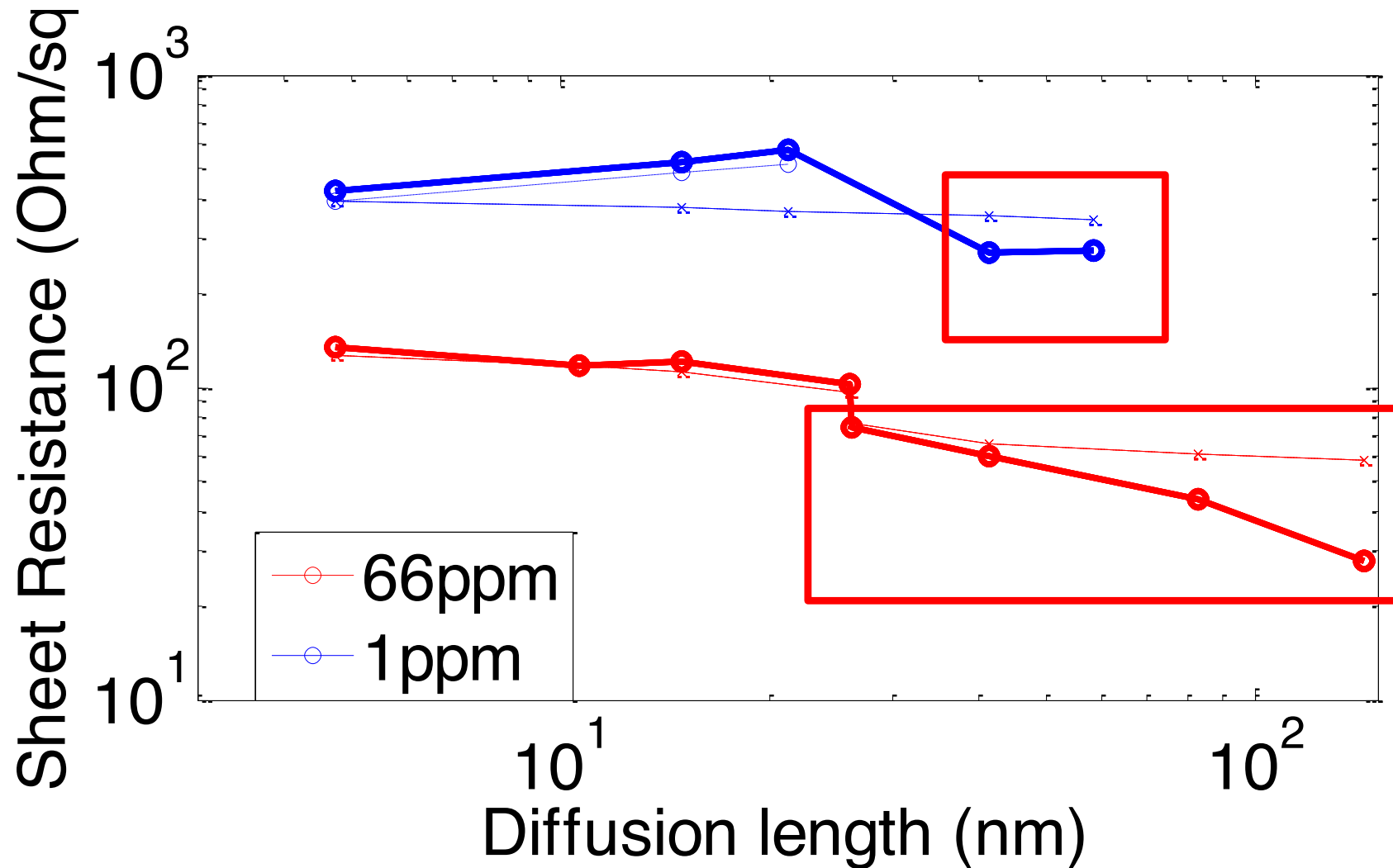
# Fitting results



# 1ppm B<sub>2</sub>H<sub>6</sub>

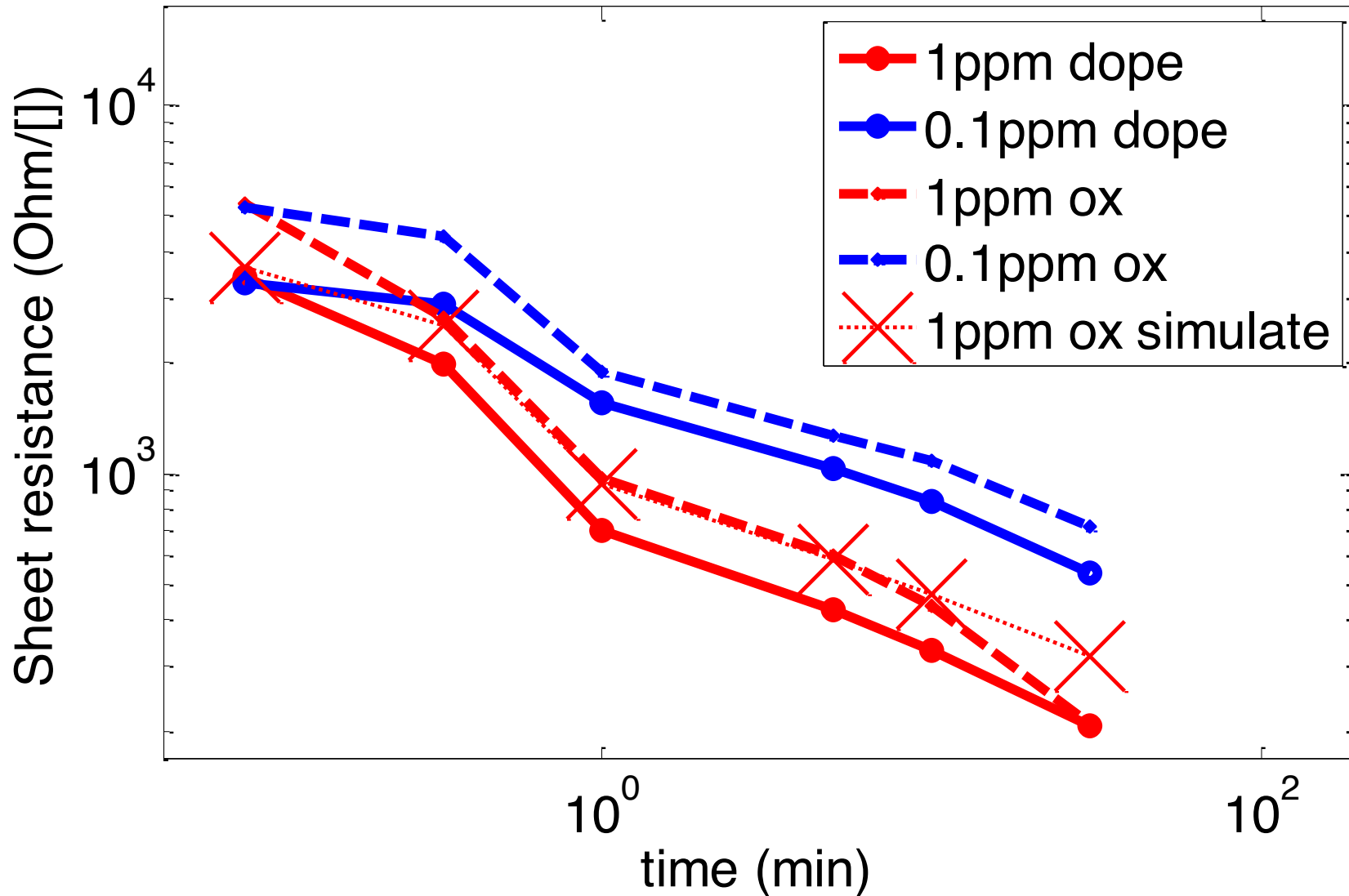


# Anneal (epi)



1ppm / 66ppm 5min doping at 900°C  
1ppm out-diffusion dominate in H<sub>2</sub> annealing  
Both has more doping when annealed at 1000°C

# Anneal (oxidation furnace)



Wet oxidation: target at 100nm oxide

Simulation match good

# Conclusion

- 2nm B<sub>x</sub>Si
  - 700°C | 6ppm | 1s-5s
  - No oxidation
- Boron doped in Silicon
  - 900°C | 0.1ppm – 1ppm | 5s – 30min
  - Oxidation OK
- Simulation code
- Variation
  - On wafer: < 3%, clear under green lamp

# Acknowledgements

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  - Ted Berg
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  - Prof. Ted Kamins
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Thank you for your time! 😊